

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.58139	100.0	8.32794
			Subtotal	0.58139	100	8.32794
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.74529	100.0	25
			Subtotal	1.74529	100	25
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02321	0.04	0.3324
	Copper alloy	Iron (Fe)	7439-89-6	0.05801	0.1	0.831
	Copper alloy	Copper (Cu)	7440-50-8	57.93225	99.86	829.8366
			Subtotal	58.01347	100	831
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.41641	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.28305	16.0	90
	Filler	Silica fused	60676-86-0	29.45178	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11781	0.3	1.6875
			Subtotal	39.26905	100	562.5
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.32113	100.0	4.6
			Subtotal	0.32113	100	4.6
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00348	5.0	0.04991
	Lead alloy	Silver (Ag)	7440-22-4	0.00174	2.5	0.02495
	Lead alloy	Lead (Pb)	7439-92-1	0.06445	92.5	0.92324
			Subtotal	0.06967	100	0.9981
			Total	100	100	1432.42604

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